

## N & P-Channel 30-V (D-S) MOSFET

### Key Features:

- Low  $r_{DS(on)}$  trench technology
- Low thermal impedance
- Fast switching speed

### Typical Applications:

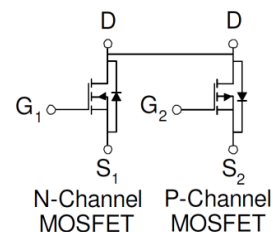
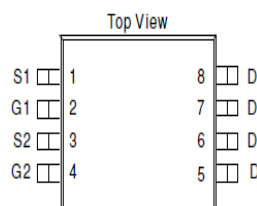
- DC/DC Conversion
- Motor Drives

PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ (m $\Omega$ )	$I_D$ (A)
30	50 @ $V_{GS} = 10V$	5.8
	83 @ $V_{GS} = 4.5V$	4.5
-30	72 @ $V_{GS} = -10V$	-4.9
	105 @ $V_{GS} = -4.5V$	-4.0



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

DFN3x3-8L



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Nch Limit	Pch Limit	Units
Drain-Source Voltage	$V_{DS}$	30	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	
Continuous Drain Current <sup>a</sup>	$I_D$	$T_A = 25^\circ\text{C}$	5.8	-4.9
		$T_A = 70^\circ\text{C}$	4.2	-3.5
Pulsed Drain Current <sup>b</sup>	$I_{DM}$	30	-30	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	3.2	-2.8	A
Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25^\circ\text{C}$	2.5	2.5
		$T_A = 70^\circ\text{C}$	1.3	1.3
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	t $\leq$ 10 sec	83
		Steady State	120

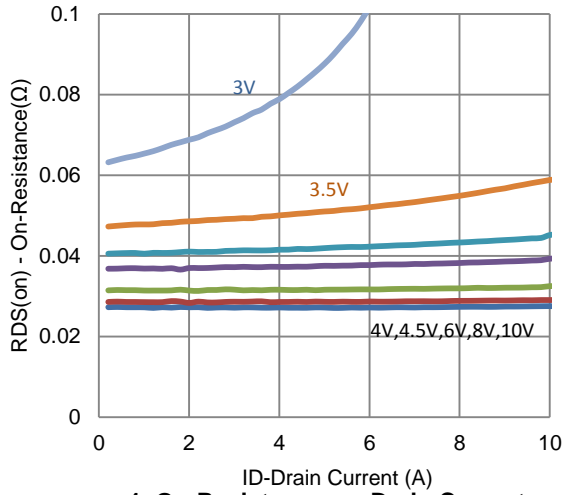
### Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

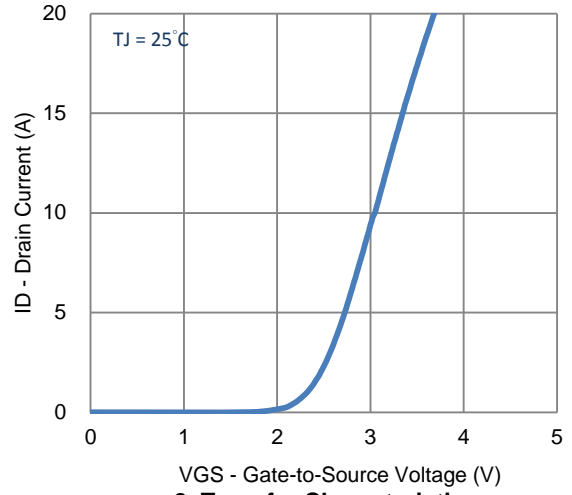
## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$ <b>(N-ch)</b>	1			V
		$V_{DS} = V_{GS}, I_D = -250 \mu A$ <b>(P-ch)</b>	-1			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24 V, V_{GS} = 0 V$ <b>(N-ch)</b>			1	uA
		$V_{DS} = -24 V, V_{GS} = 0 V$ <b>(P-ch)</b>			-1	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$I_S = 5 V, V_{GS} = 10 V$ <b>(N-ch)</b>	7.5			A
		$V_{DS} = -5 V, V_{GS} = -10 V$ <b>(P-ch)</b>	-7.5			A
Drain-Source On-Resistance <sup>a</sup>	$r_{DS(on)}$	$V_{GS} = 10 V, I_D = 4.6 A$ <b>(N-ch)</b>			50	mΩ
		$V_{GS} = 4.5 V, I_D = 3.7 A$ <b>(N-ch)</b>			83	
		$V_{GS} = -10 V, I_D = -3.8 A$ <b>(P-ch)</b>			72	mΩ
		$V_{GS} = -4.5 V, I_D = -3.1 A$ <b>(P-ch)</b>			105	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15 V, I_D = 4.6 A$ <b>(N-ch)</b>		9		S
		$V_{DS} = -15 V, I_D = -3.8 A$ <b>(P-ch)</b>		8		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 1.6 A, V_{GS} = 0 V$ <b>(N-ch)</b>		0.78		V
		$I_S = -1.4 A, V_{GS} = 0 V$ <b>(P-ch)</b>		-0.83		V
<b>Dynamic <sup>b</sup></b>						
Total Gate Charge	$Q_g$	N - Channel $V_{DS} = 15 V, V_{GS} = 4.5 V,$ $I_D = 4.6 A$		4.4		nC
Gate-Source Charge	$Q_{gs}$			1.1		
Gate-Drain Charge	$Q_{gd}$			2.2		
Turn-On Delay Time	$t_{d(on)}$	N - Channel $V_{DS} = 15 V, R_L = 3.3 \Omega, I_D = 4.6 A,$ $V_{GEN} = 10 V, R_{GEN} = 6 \Omega$		3		ns
Rise Time	$t_r$			11		
Turn-Off Delay Time	$t_{d(off)}$			17		
Fall Time	$t_f$			5		
Input Capacitance	$C_{iss}$	N - Channel $V_{DS} = 15 V, V_{GS} = 0 V, f = 1 \text{ Mhz}$		360		pF
Output Capacitance	$C_{oss}$			56		
Reverse Transfer Capacitance	$C_{rss}$			46		
Total Gate Charge	$Q_g$	P - Channel $V_{DS} = -15 V, V_{GS} = -4.5 V,$ $I_D = -3.8 A$		4.4		nC
Gate-Source Charge	$Q_{gs}$			0.7		
Gate-Drain Charge	$Q_{gd}$			2.6		
Turn-On Delay Time	$t_{d(on)}$	P - Channel $V_{DS} = -15 V, R_L = 4 \Omega, I_D = -3.8 A,$ $V_{GEN} = -10 V, R_{GEN} = 6 \Omega$		4		ns
Rise Time	$t_r$			20		
Turn-Off Delay Time	$t_{d(off)}$			19		
Fall Time	$t_f$			10		
Input Capacitance	$C_{iss}$	P - Channel $V_{DS} = -15 V, V_{GS} = 0 V, f = 1 \text{ Mhz}$		467		pF
Output Capacitance	$C_{oss}$			73		
Reverse Transfer Capacitance	$C_{rss}$			58		

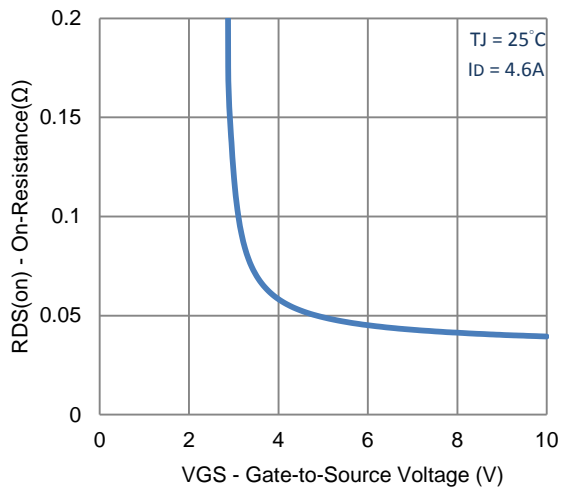
Typical Electrical Characteristics - N-channel



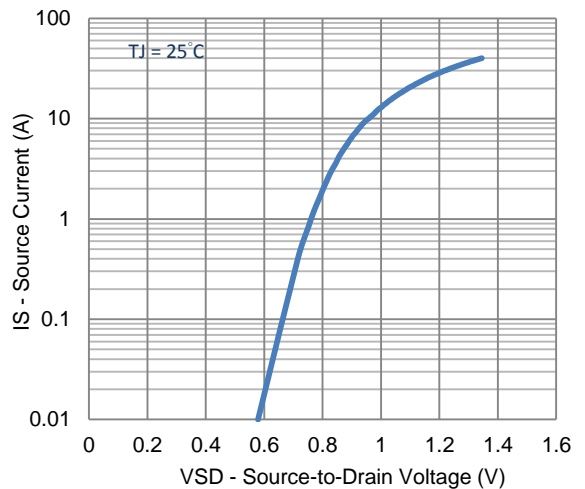
1. On-Resistance vs. Drain Current



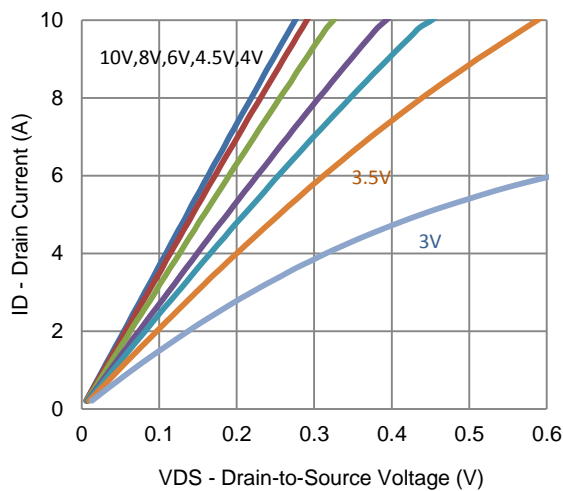
2. Transfer Characteristics



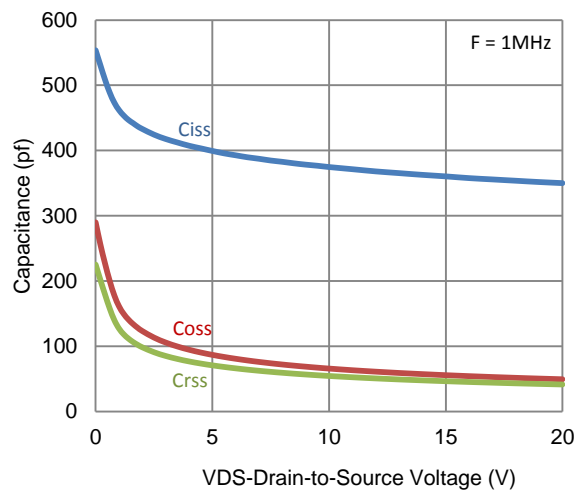
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

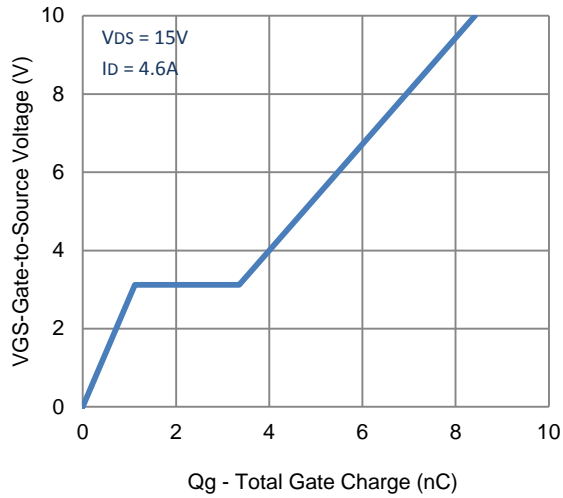


5. Output Characteristics

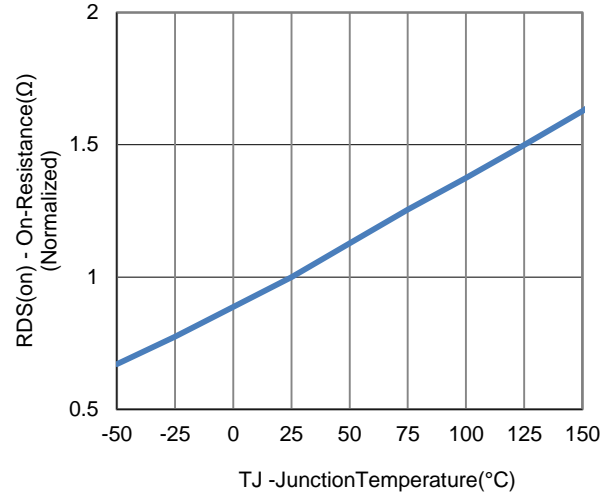


6. Capacitance

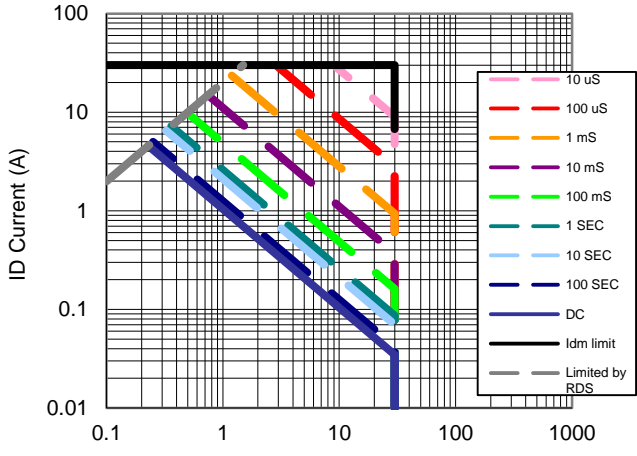
Typical Electrical Characteristics - N-channel



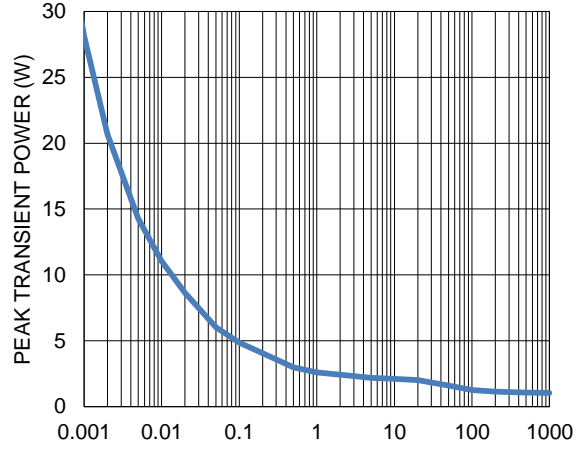
7. Gate Charge



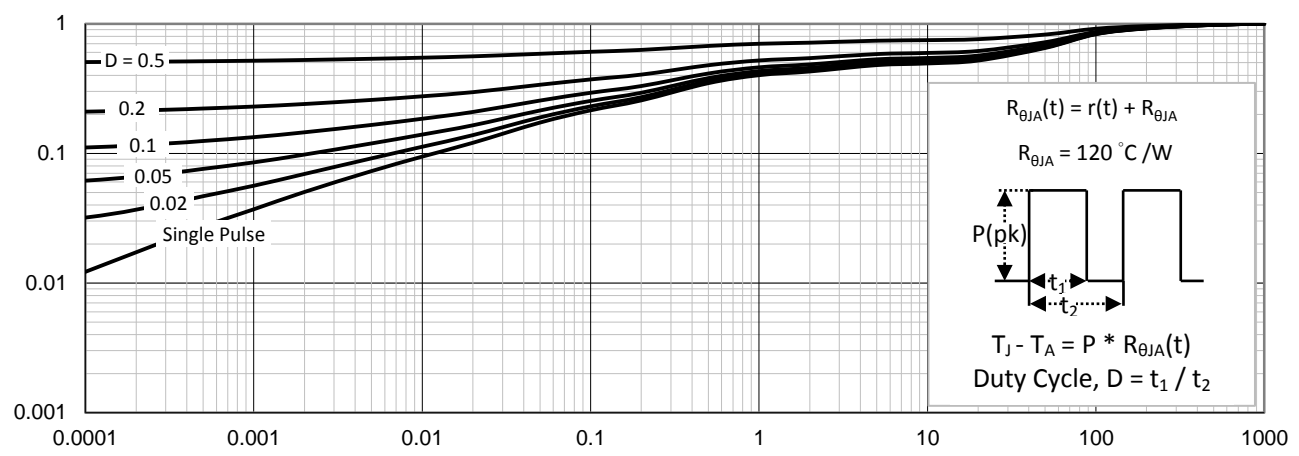
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

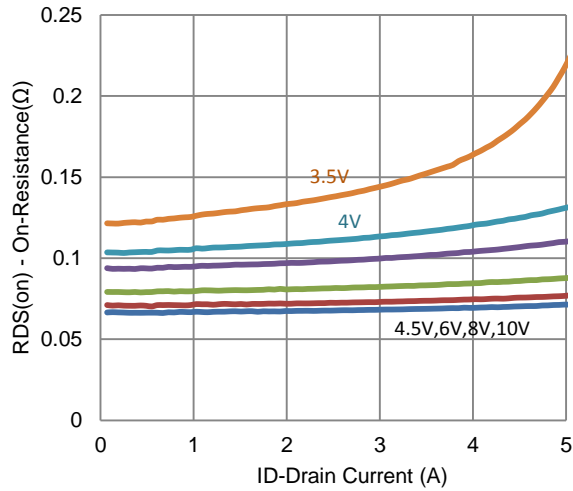


10. Single Pulse Maximum Power Dissipation

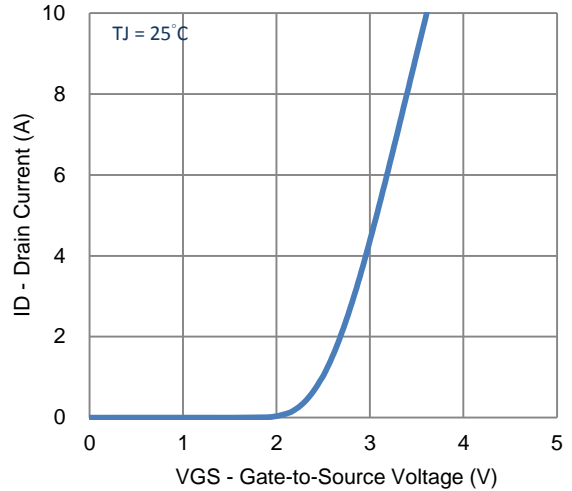


11. Normalized Thermal Transient Junction to Ambient

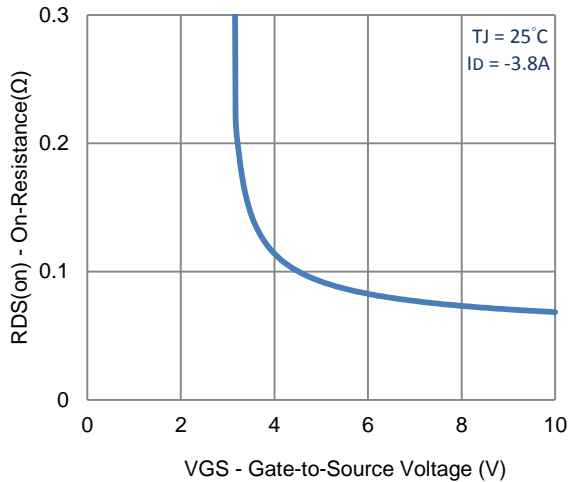
Typical Electrical Characteristics - P-channel



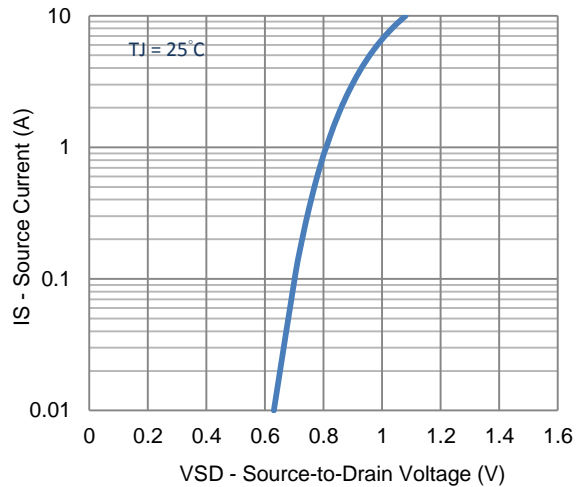
1. On-Resistance vs. Drain Current



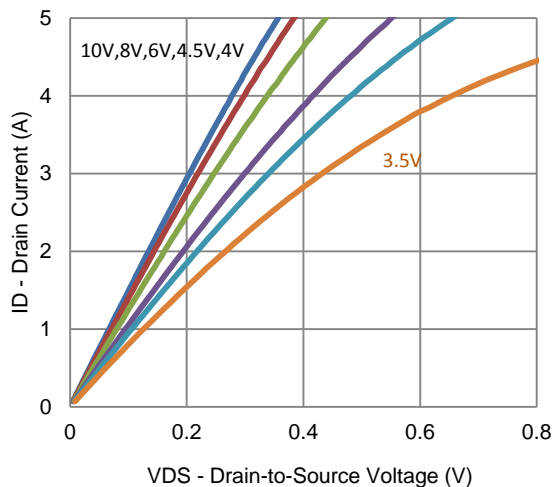
2. Transfer Characteristics



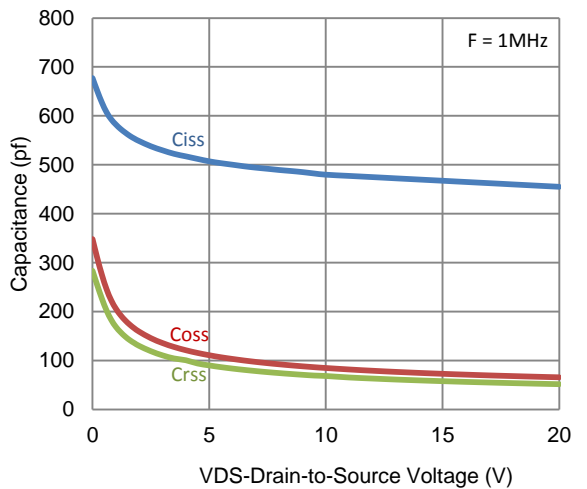
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

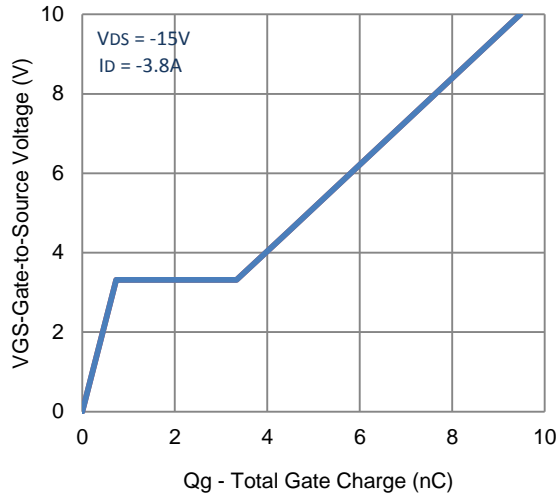


5. Output Characteristics

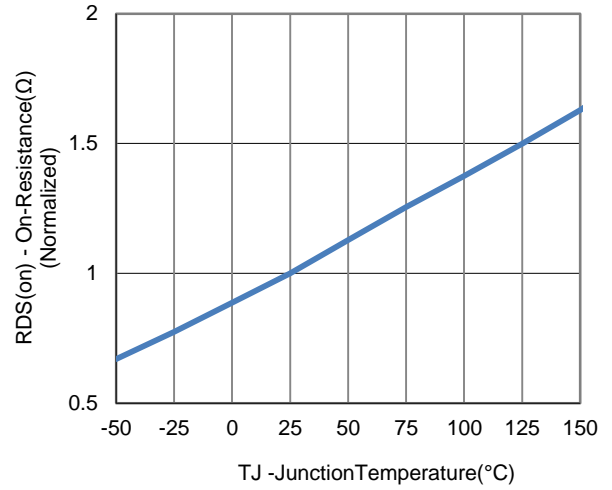


6. Capacitance

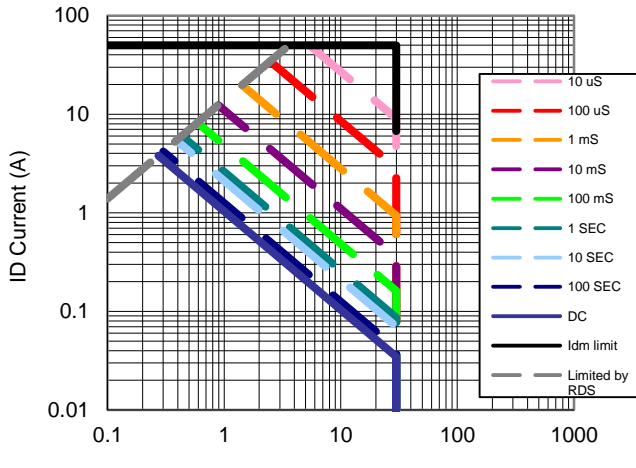
Typical Electrical Characteristics - P-channel



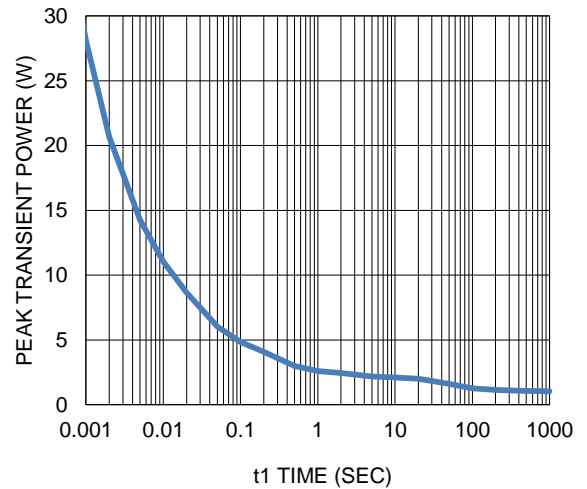
7. Gate Charge



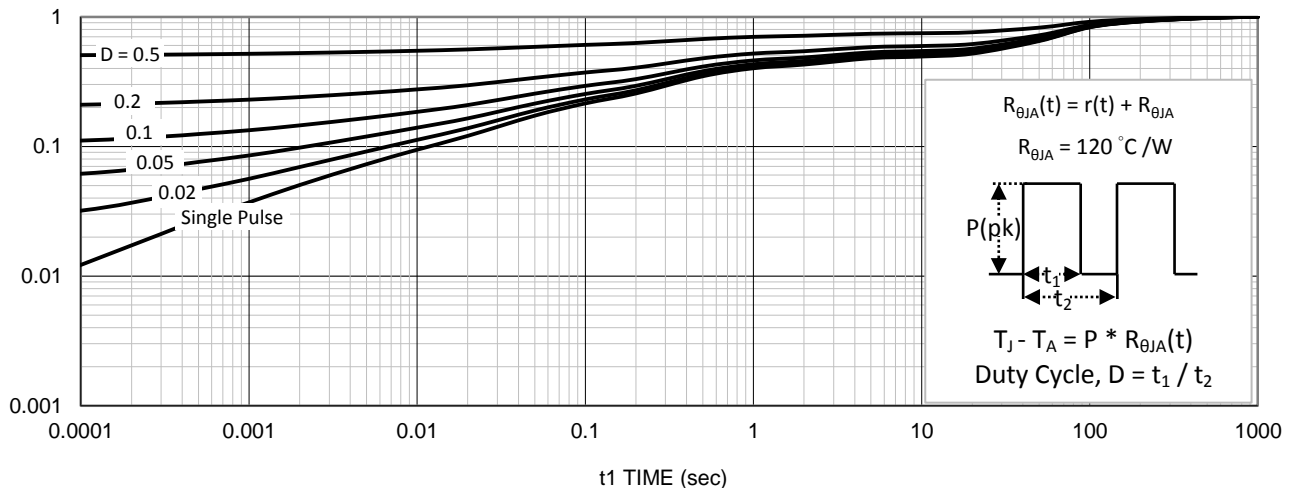
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

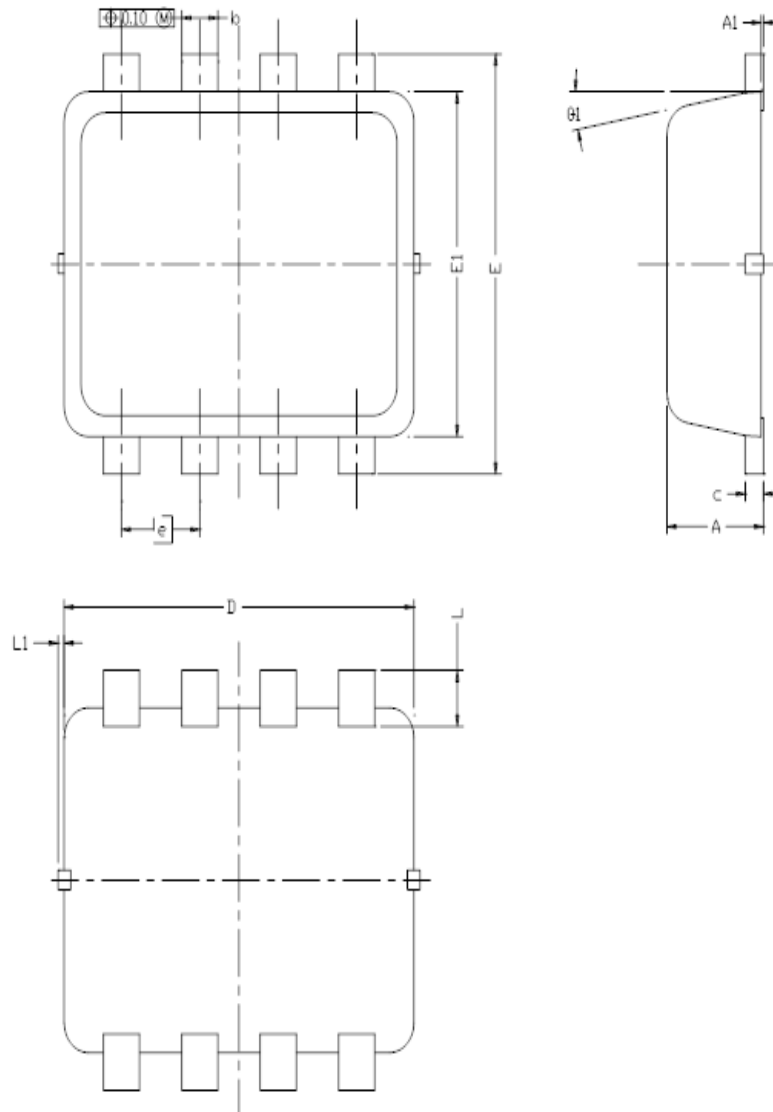


10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient

Package Information



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.80	0.90	0.0276	0.0315	0.0354
A1	0.00	---	0.05	0.000	---	0.002
b	0.24	0.30	0.35	0.009	0.012	0.014
c	0.10	0.152	0.25	0.004	0.006	0.010
D	3.00 BSC			0.118 BSC		
D1	2.475 BSC			0.093 BSC		
D2	1.063 BSC			0.042 BSC		
D3	0.225 BSC			0.009 BSC		
E	3.20 BSC			0.126 BSC		
E1	3.00 BSC			0.118 BSC		
E2	1.813 BSC			0.069 BSC		
E3	0.525 BSC			0.023 BSC		
e	0.65 BSC			0.026 BSC		
L	0.30	0.40	0.50	0.0118	0.0157	0.0197
L1	0	---	0.100	0	---	0.004
-	0?	10?	12?	0?	10?	12?